



**THE DATASHEET OF  
SN74ABT162244DL**

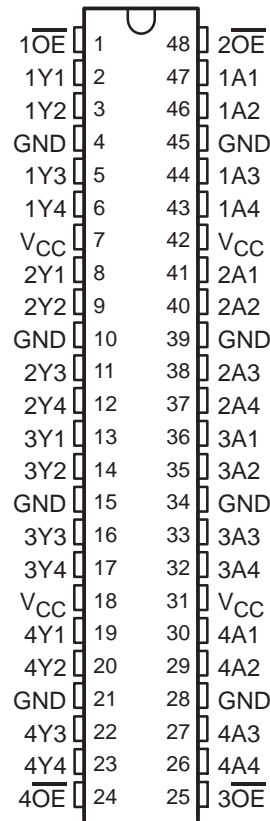


# SN54ABT162244, SN74ABT162244 16-BIT BUFFERS/DRIVERS WITH 3-STATE OUTPUTS

SCBS238E – JUNE 1992 – REVISED JUNE 2004

- Members of the Texas Instruments Widebus™ Family
- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- Typical  $V_{OLP}$  (Output Ground Bounce) <1 V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- High-Impedance State During Power Up and Power Down
- $I_{off}$  and Power-Up 3-State Support Hot Insertion
- Distributed  $V_{CC}$  and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD-17

SN54ABT162244 . . . WD PACKAGE  
SN74ABT162244 . . . DGG, DGV, OR DL PACKAGE  
(TOP VIEW)



## description/ordering information

The 'ABT162244 devices are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide noninverting outputs and symmetrical active-low output-enable ( $\overline{OE}$ ) inputs.

The outputs, which are designed to source or sink up to 12 mA, include equivalent 25-Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP – DL	Tube	SN74ABT162244DL	ABT162244
		Tape and reel	SN74ABT162244DLR	
	TSSOP – DGG	Tape and reel	SN74ABT162244DGGR	ABT162244
-55°C to 125°C	TVSOP – DGV	Tape and reel	SN74ABT162244DGV	AH2244
	CFP – WD	Tube	SNJ54ABT162244WD	SNJ54ABT162244WD

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54ABT162244, SN74ABT162244

## 16-BIT BUFFERS/DRIVERS

### WITH 3-STATE OUTPUTS

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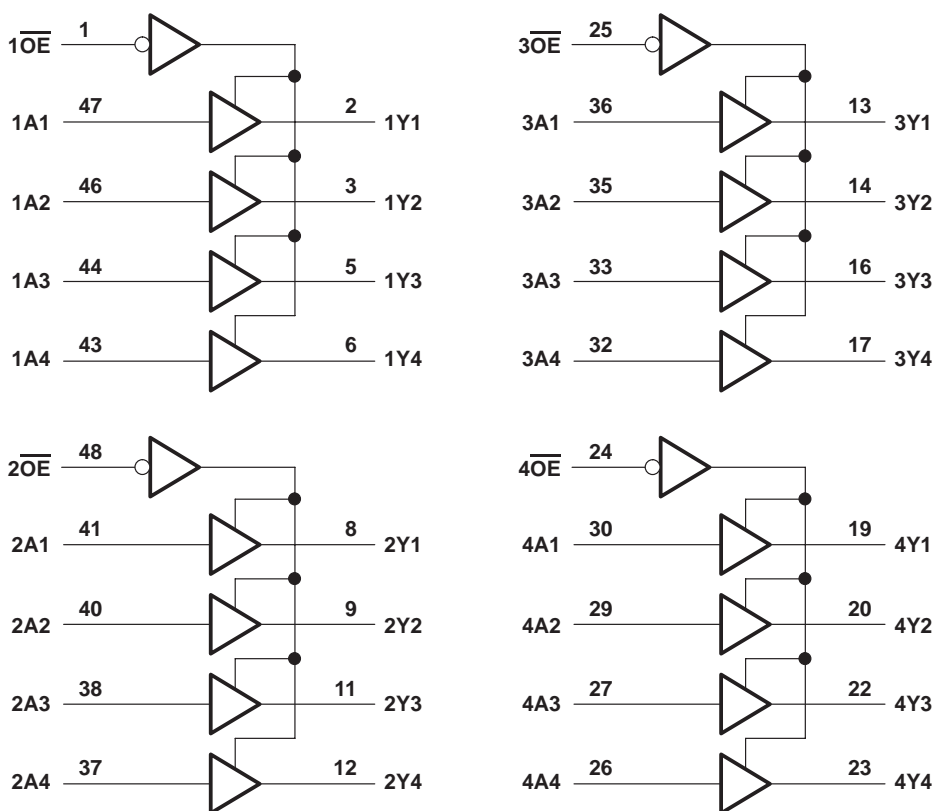
#### description/ordering information (continued)

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

FUNCTION TABLE  
(each 4-bit buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	H
L	L	L
H	X	Z

#### logic diagram (positive logic)





# SN54ABT162244, SN74ABT162244

## 16-BIT BUFFERS/DRIVERS

### WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T <sub>A</sub> = 25°C			SN54ABT162244		SN74ABT162244		UNIT	
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX		
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.2		-1.2		-1.2	V	
V <sub>OH</sub>	V <sub>CC</sub> = 4.5 V, I <sub>OH</sub> = -1 mA			3.35		3.35		3.35	V	
	V <sub>CC</sub> = 5 V, I <sub>OH</sub> = -1 mA			3.85		3.85		3.85		
	V <sub>CC</sub> = 4.5 V	I <sub>OH</sub> = -3 mA			3.1		3.1			3.1
I <sub>OH</sub> = -12 mA				2.6*				2.6		
V <sub>OL</sub>	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 8 mA			0.4		0.8	0.65	V	
		I <sub>OL</sub> = 12 mA					0.8*	0.8		
V <sub>hys</sub>				100					mV	
I <sub>I</sub>	V <sub>CC</sub> = 0 to 5.5 V, V <sub>I</sub> = V <sub>CC</sub> or GND			±1		±1		±1	µA	
I <sub>OZPU</sub>	V <sub>CC</sub> = 0 to 2.1 V, V <sub>O</sub> = 0.5 V to 2.7 V, $\overline{OE} = X$			±50		±50		±50	µA	
I <sub>OZPD</sub>	V <sub>CC</sub> = 2.1 V to 0, V <sub>O</sub> = 0.5 V to 2.7 V, $\overline{OE} = X$			±50		±50		±50	µA	
I <sub>OZH</sub>	V <sub>CC</sub> = 2.1 V to 5.5 V, V <sub>O</sub> = 2.7 V, $\overline{OE} \geq 2$ V			10		10		10	µA	
I <sub>OZL</sub>	V <sub>CC</sub> = 2.1 V to 5.5 V, V <sub>O</sub> = 0.5 V, $\overline{OE} \geq 2$ V			-10		-10		-10	µA	
I <sub>off</sub>	V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> ≤ 4.5 V			±100				±100	µA	
I <sub>CEX</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 5.5 V	Outputs high			50	50		50	µA	
I <sub>O</sub>	V <sub>CC</sub> = 5.5 V, V <sub>O</sub> = 2.5 V			-25 -55 -100		-25 -100		-25 -100	mA	
I <sub>CC</sub> ‡	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND	Outputs high			2	2		2	mA	
		Outputs low			30	30		30		
		Outputs disabled			2	2		2		
ΔI <sub>CC</sub> §	Data inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND	Outputs enabled			50	50		50	µA
			Outputs disabled			50	50		50	
	Control inputs	V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			50	50		50		
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V			3					pF	
C <sub>o</sub>	V <sub>O</sub> = 2.5 V or 0.5 V			8					pF	

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at V<sub>CC</sub> = 5 V.

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V<sub>CC</sub> or GND.



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**16-BIT BUFFERS/DRIVERS**  
**WITH 3-STATE OUTPUTS**

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT162244					UNIT	
			$V_{CC} = 5$ V, $T_A = 25^\circ$ C			MIN	MAX		
			MIN	TYP	MAX				
t <sub>PLH</sub>	A	Y	1	2.5	3.6	1	4.1	ns	
t <sub>PHL</sub>			1	3.1	4.7	1	5.3		
t <sub>PZH</sub>	$\overline{OE}$	Y	1	3.2	4.8	1	5.6	ns	
t <sub>PZL</sub>			1	3.2	4.7	1	5.5		
t <sub>PHZ</sub>	$\overline{OE}$	Y	1	3.2	5.3	1	6.3	ns	
t <sub>PLZ</sub>			1	3.1	4.6	1	4.9		

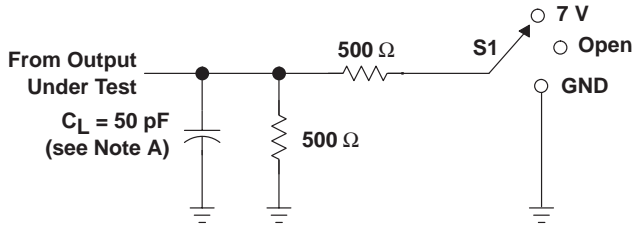
switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50$  pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT162244					UNIT	
			$V_{CC} = 5$ V, $T_A = 25^\circ$ C			MIN	MAX		
			MIN	TYP	MAX				
t <sub>PLH</sub>	A	Y	1	2.5	3.2	1	3.9	ns	
t <sub>PHL</sub>			1	3.1	4	1	4.8		
t <sub>PZH</sub>	$\overline{OE}$	Y	1	3.2	4.2	1	5.4	ns	
t <sub>PZL</sub>			1	3.2	4.1	1	5.1		
t <sub>PHZ</sub>	$\overline{OE}$	Y	1	3.2	4	1	4.6	ns	
t <sub>PLZ</sub>			1	3.1	3.9	1	4.5		

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**WITH 3-STATE OUTPUTS**

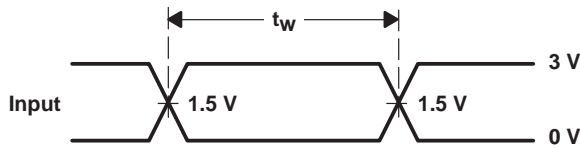
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**PARAMETER MEASUREMENT INFORMATION**

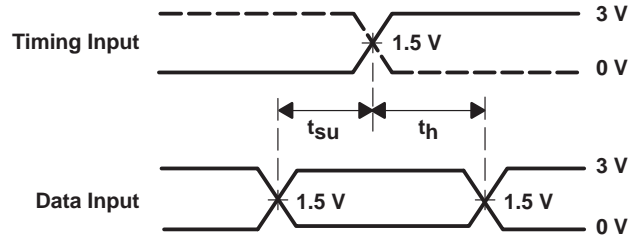


**LOAD CIRCUIT**

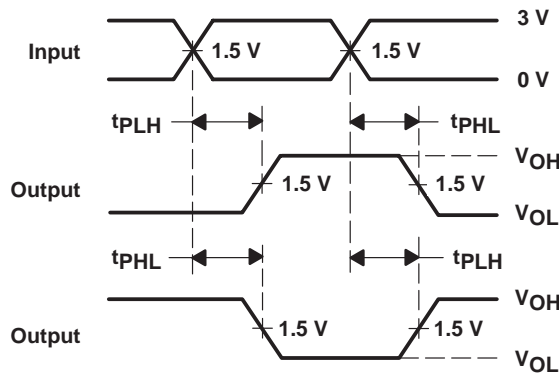
TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



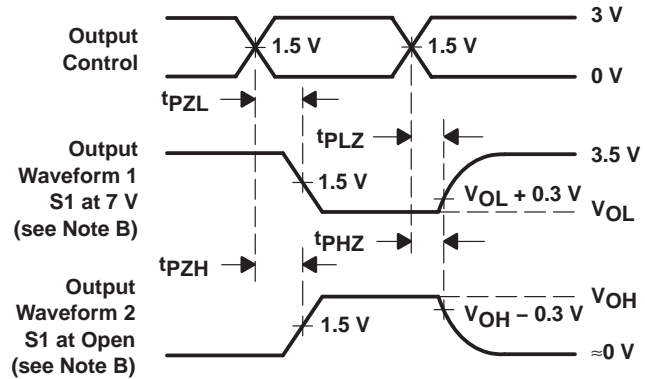
**VOLTAGE WAVEFORMS  
 PULSE DURATION**



**VOLTAGE WAVEFORMS  
 SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS  
 PROPAGATION DELAY TIMES  
 INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS  
 ENABLE AND DISABLE TIMES  
 LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9458701QXA	ACTIVE	CFP	WD	48	15	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9458701QX A SNJ54ABT162244 WD	<a href="#">Samples</a>
74ABT162244DGGRG4	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162244	<a href="#">Samples</a>
SN74ABT162244DGGR	ACTIVE	TSSOP	DGG	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162244	<a href="#">Samples</a>
SN74ABT162244DGVR	ACTIVE	TVSOP	DGV	48	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AH2244	<a href="#">Samples</a>
SN74ABT162244DL	ACTIVE	SSOP	DL	48	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162244	<a href="#">Samples</a>
SN74ABT162244DLR	ACTIVE	SSOP	DL	48	1000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT162244	<a href="#">Samples</a>
SNJ54ABT162244WD	ACTIVE	CFP	WD	48	15	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9458701QX A SNJ54ABT162244 WD	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF SN54ABT162244, SN74ABT162244 :**

● Catalog : [SN74ABT162244](#)

● Military : [SN54ABT162244](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT162244DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74ABT162244DGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74ABT162244DLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT162244DGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0
SN74ABT162244DGVR	TVSOP	DGV	48	2000	356.0	356.0	35.0
SN74ABT162244DLR	SSOP	DL	48	1000	367.0	367.0	55.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN74ABT162244DL	DL	SSOP	48	25	473.7	14.24	5110	7.87

# MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MO-118

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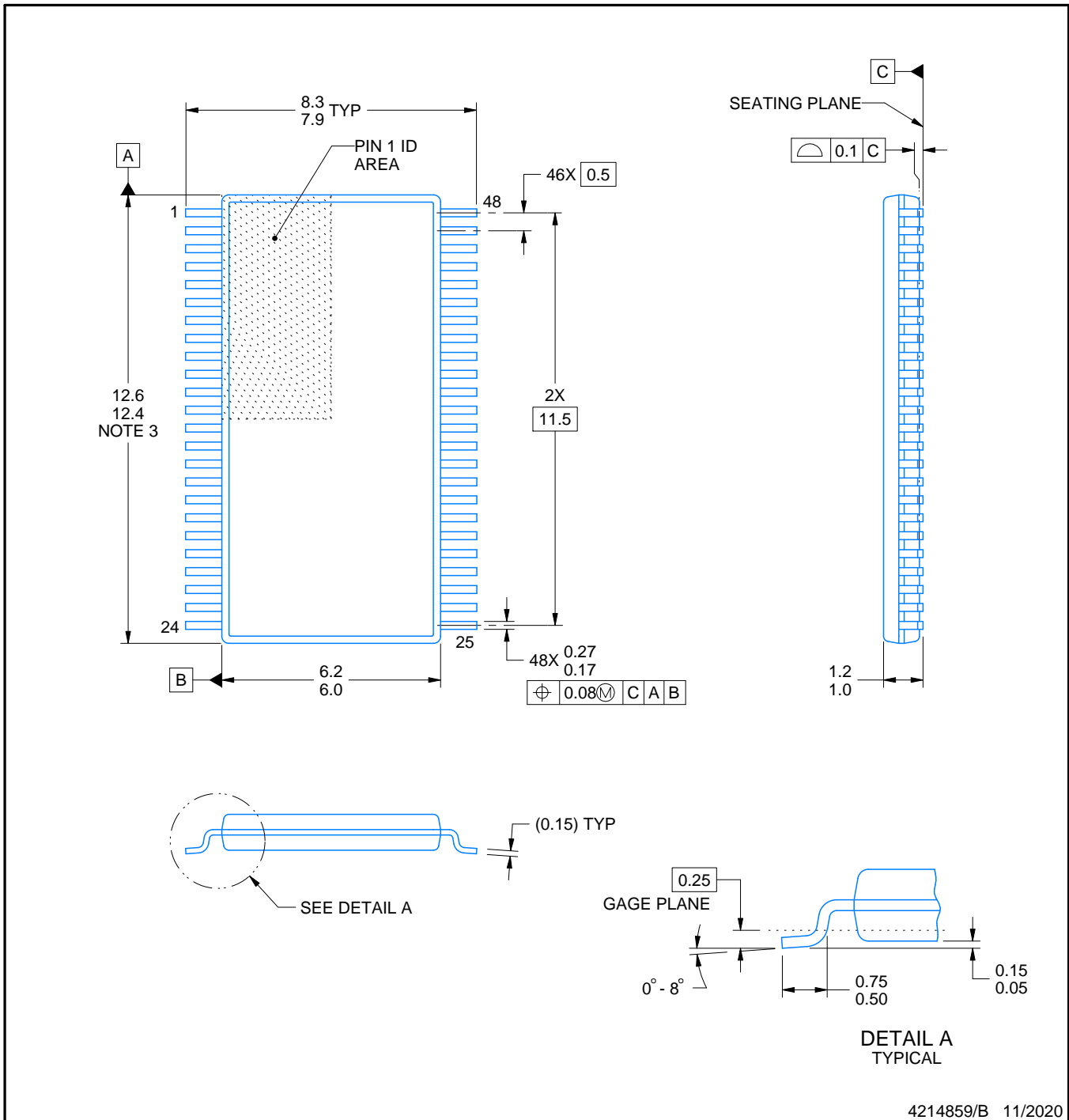
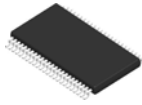
DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194



4214859/B 11/2020

NOTES:

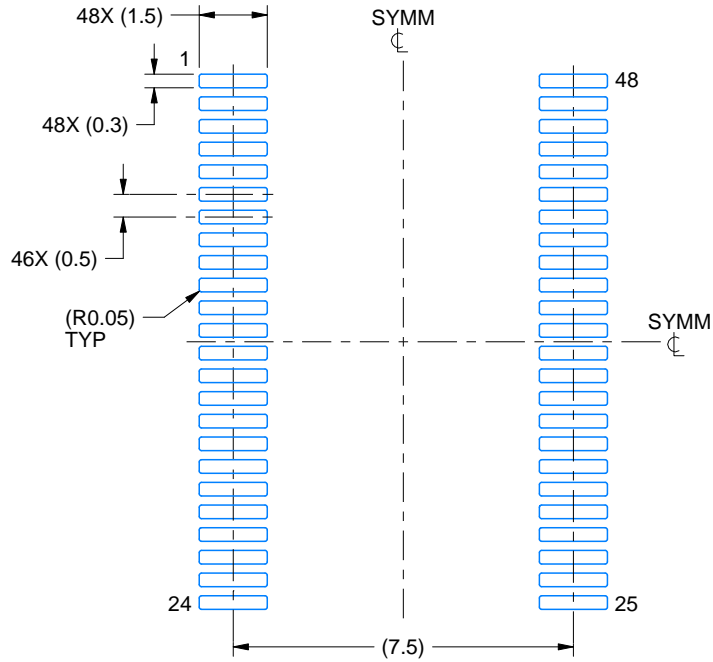
- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
- Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

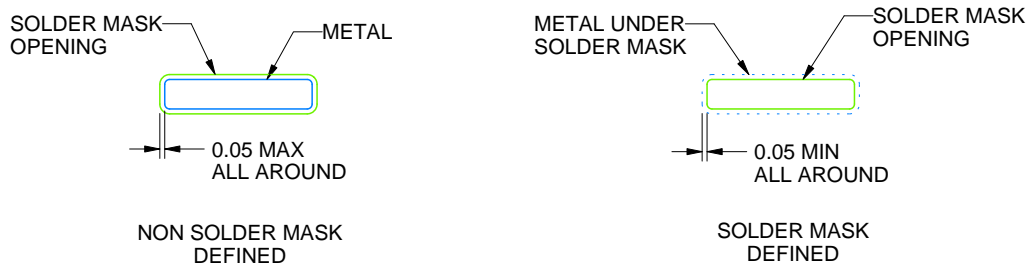
DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

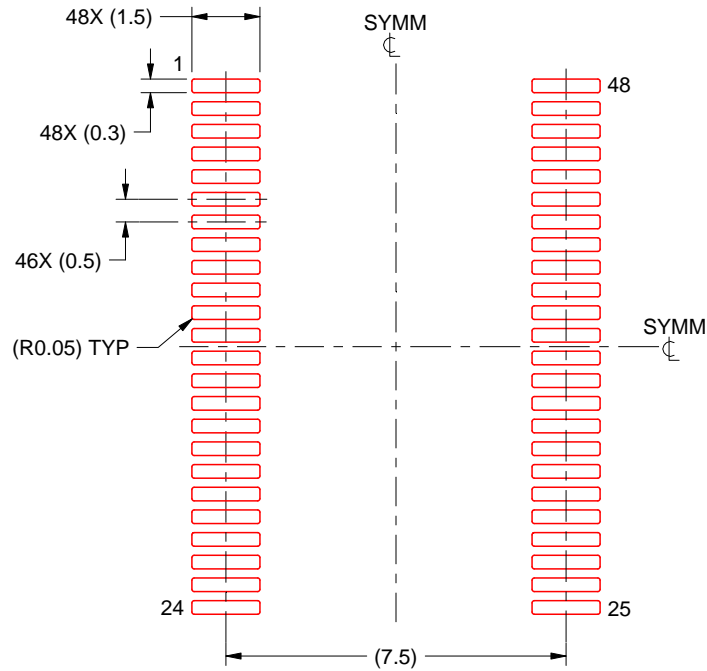
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DGG0048A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

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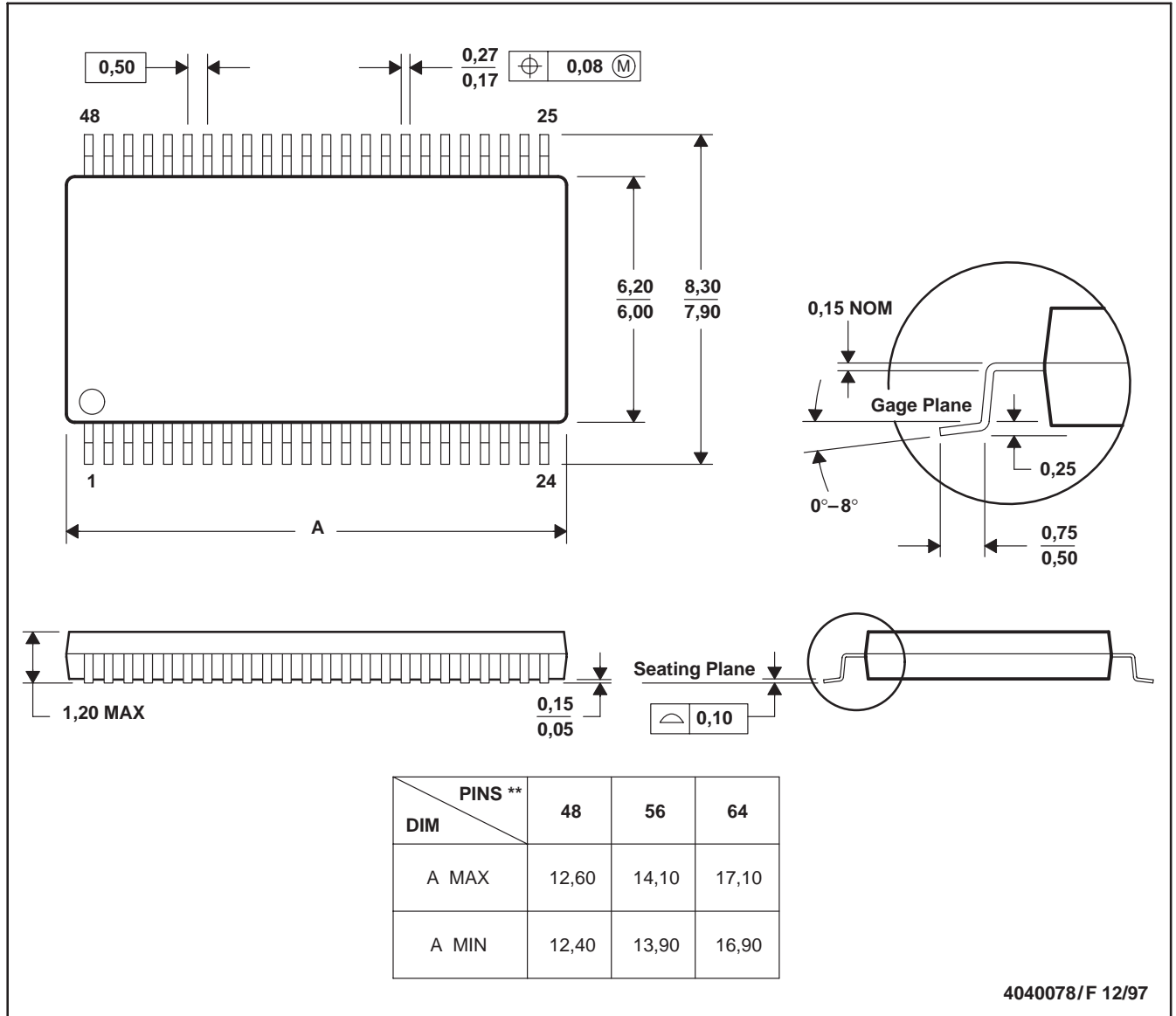
NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DGG (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

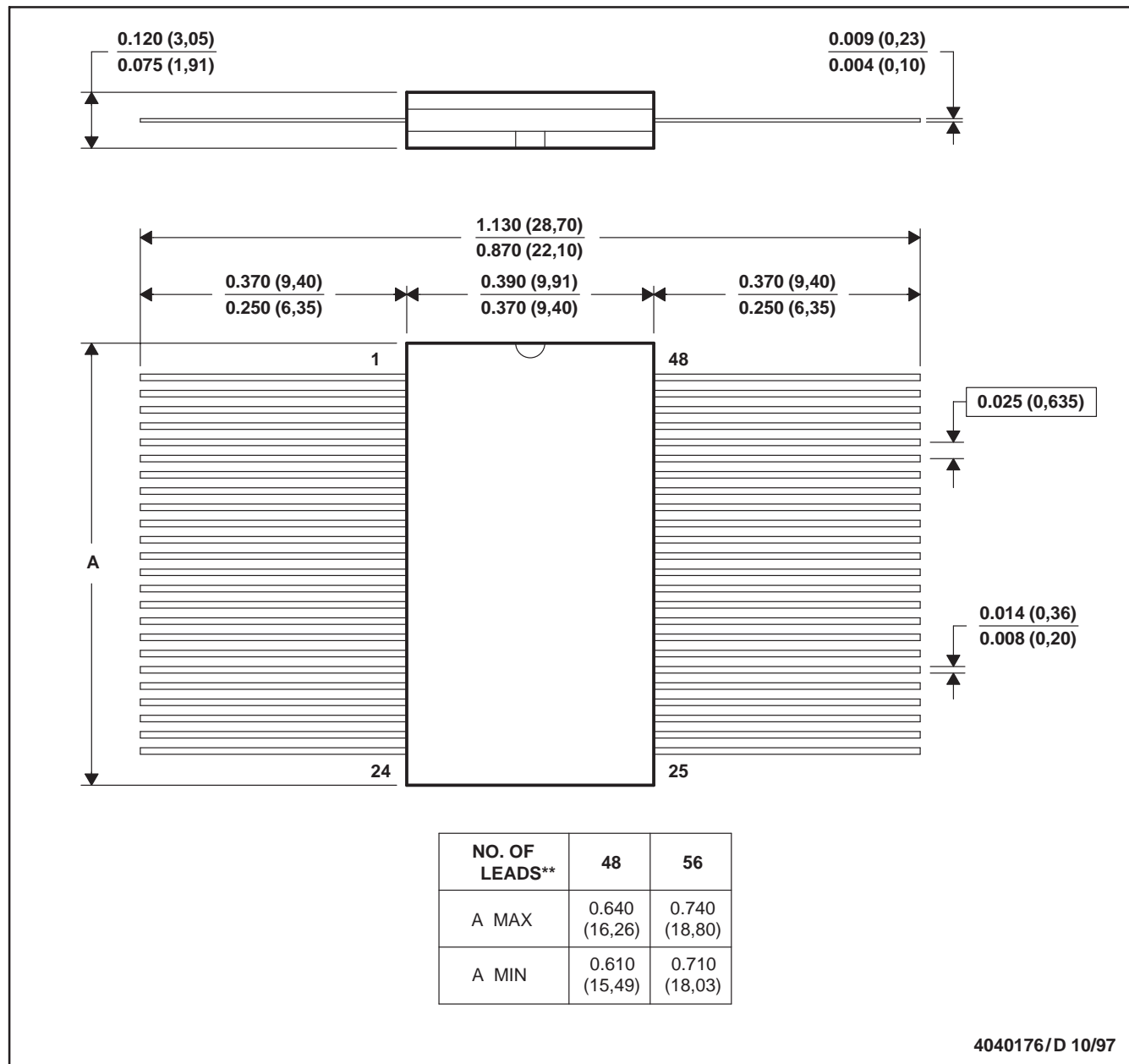


- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

WD (R-GDFP-F\*\*)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only  
 E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA  
 GDFP1-F56 and JEDEC MO-146AB

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